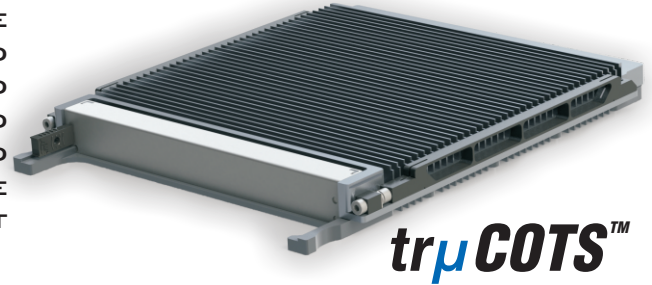
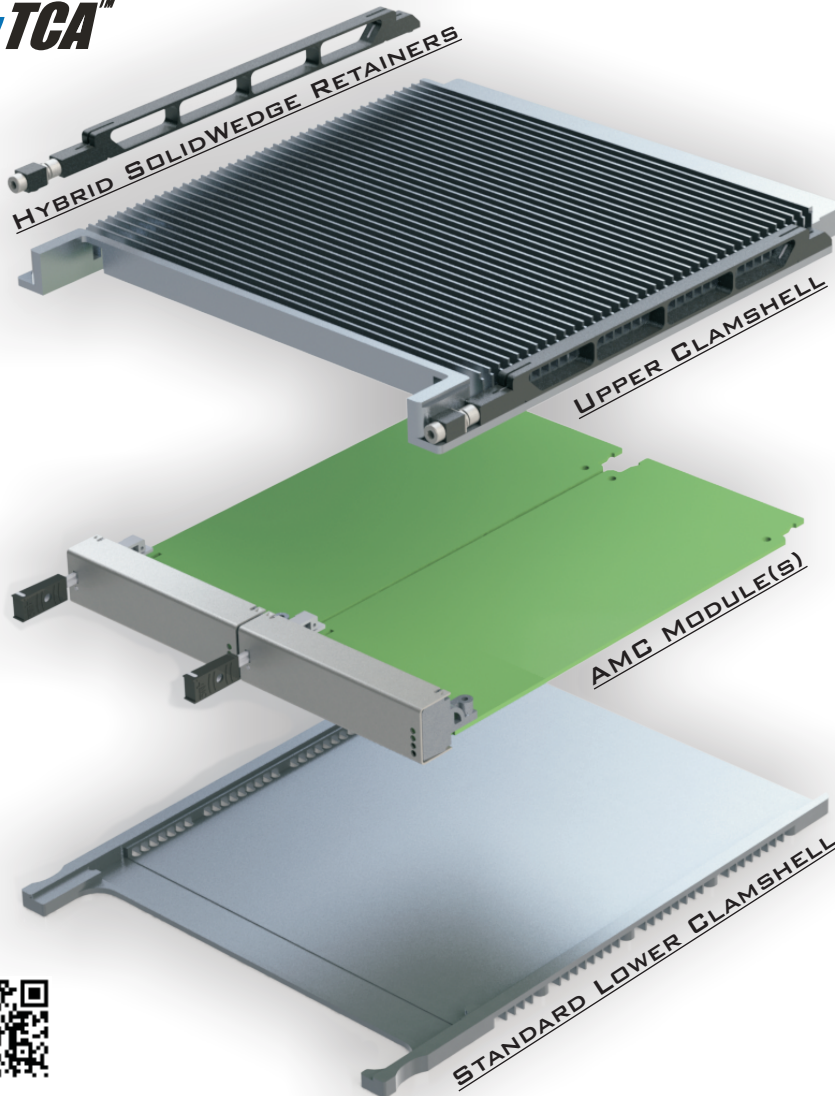


THE AMC DEVELOPMENT KIT PROVIDES THE ARCHITECTURE AND COMPONENTS TO FACILITATE RAPID DEVELOPMENT OF A HARDENED AIR-COOLED MICROTCA.2 MODULE. OUR CLEARLY DEFINED PROCESS FOR MIGRATION TO CONDUCTION COOLED MODULES PROVIDES BUILDING BLOCKS WHICH ARE REUSABLE ACROSS MULTIPLE PRODUCT DEVELOPMENT CYCLES.



μ TCA™



FEATURES:

- COMPLIES TO MTCA.2 DRAFT
- CONDUCTION / CONVECTION
- OPEN SHELL DESIGN
- FITS 1 DOUBLE WIDE AMC MODULE OR 2 SINGLE WIDE
- CUSTOMIZABLE HEAT PLATE

STANDARD SIZES:

- HALF HEIGHT MODULES
- MID HEIGHT MODULES
- FULL HEIGHT MODULES
- POWER MODULE
- MCH MODULE

KIT INCLUDES:

- UPPER CLAMSHELL
- LOWER CLAMSHELL
- 2 HYBRID-SOLIDWEDGE CARD RETAINERS
- THERMAL INTERFACE MATERIAL
- ASSEMBLY HARDWARE
- 3D MODELS AVAILABLE

MATERIALS:

ALUMINUM 6061-T6

- UPPER CLAMSHELL
- LOWER CLAMSHELL
- HYBRID-SOLIDWEDGE

300 SERIES STAINLESS STEEL

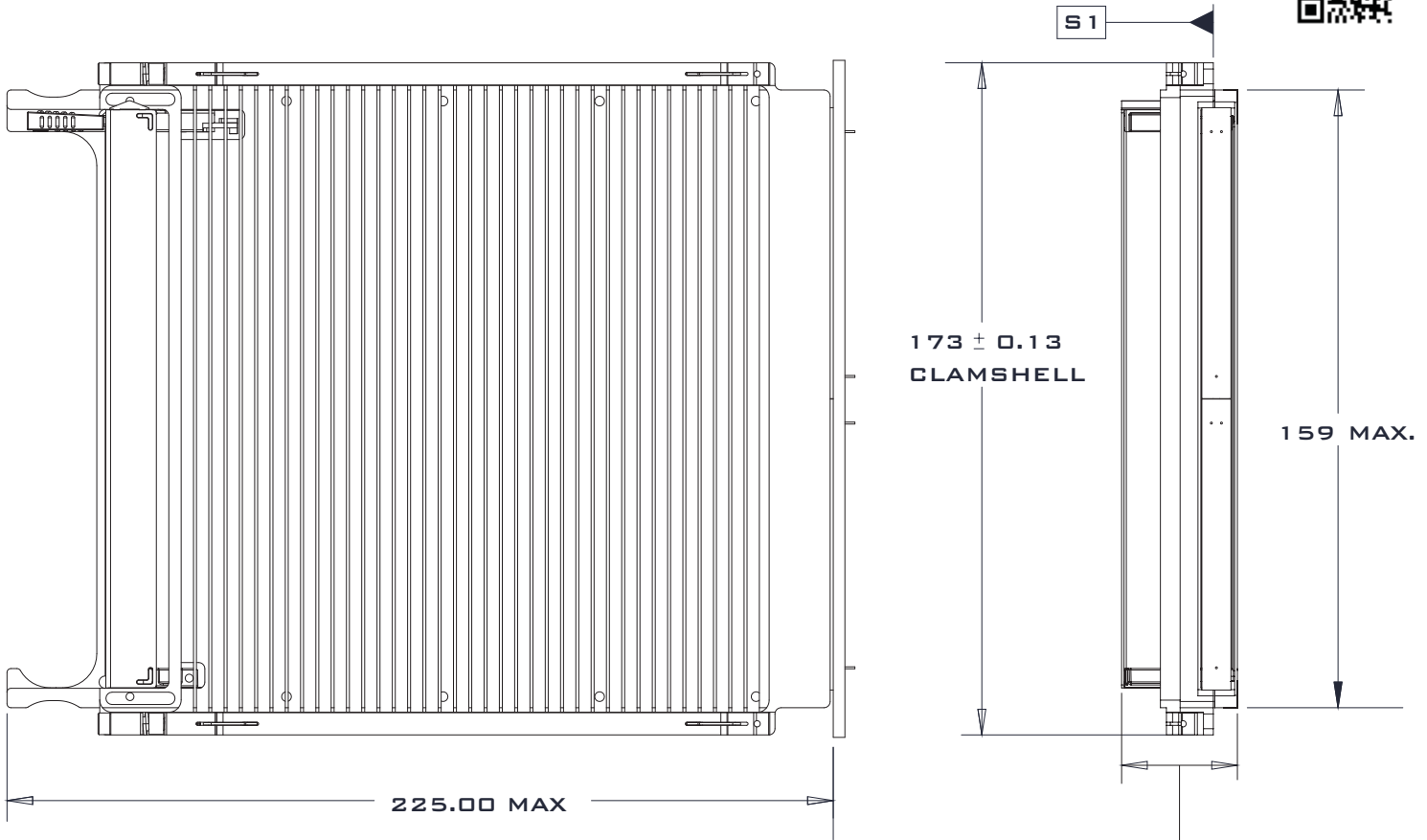
- ALL FASTENERS

MICROTCA.2 IS A SYSTEM-LEVEL, MISSION-CRITICAL ARCHITECTURE/SPECIFICATION FROM PICMG WHICH OFFERS GUIDELINES FOR DEVELOPMENT OF COTS AMC COMPUTING MODULES, AND THEIR HOST ENVIRONMENT. AMC MODULES ARE USED ACROSS SEVERAL MARKET SEGMENTS/APPLICATIONS, EFFECTING A NATURAL COST REDUCTION DUE TO BEING MANUFACTURED IN HIGHER VOLUME, AND ARE IDEALLY SUITED FOR TODAY'S MODERN MISSION-CRITICAL APPLICATIONS IN TERMS OF PERFORMANCE AND BUDGET.

WAVETHERM'S TRUCOTS PRODUCTS ARE INTENDED TO REDUCE NRE COSTS ASSOCIATED WITH DEVELOPMENT OF RUGGED AMC MODULE MECHANICAL ASSEMBLIES, WHILE IMPROVING BOARD AND SYSTEM PERFORMANCE THROUGH SUPERIOR DESIGN. THE INTEROPERABILITY OF MICROTCA PRODUCTS HAVE BEEN PROVEN BY NUMEROUS COMPANIES IN BOTH LABORATORY AND FIELD APPLICATIONS.

DIMENSIONS (MM):

truCOTS™



- COMPACT HEIGHT- 3HP (0.60", 15.24MM)
- MID-HEIGHT- 4HP (0.80", 20.32MM)
- FULL HEIGHT- 6HP (1.20", 30.48MM)
- POWER MODULE- 7HP (1.40", 35.56MM)
- MCH MODULE- (1.45", 37.00MM)

BASED ON THE MICROTCA. DRAFT SPECIFICATION, THE CONDUCTION COOLED DEVELOPMENT KIT IS DESIGNED FOR RAPID DEVELOPMENT AND TESTING OF AMC MODULES. MOST AMC MODULES WILL FIT INSIDE ONE OF THE THREE STANDARD UPPER CLAMSHELLS. THERMAL INTERFACE MATERIAL OR THERMAL PUTTY CAN FILL THE OPEN SPACE OF THE UPPER AND LOWER CLAMSHELLS TO TRANSFER HEAT TO THE CARD EDGE FOR LOWER WATTAGE AMC MODULES. FOR HIGHER WATTAGE MODULES, A STANDARD 2.5MM MOUNTING PATTERN IN THE UPPER CLAMSHELL SUPPORTS CUSTOMIZABLE HEAT PLATES THAT CAN BE SKY-LINED TO HIGH WATTAGE COMPONENTS TO REDUCE THE THERMAL RESISTANCE TO THE UPPER CLAMSHELL. FOR EXTREMELY HIGH WATTAGE MODULES, OR MODULES THAT WILL NOT FIT ONE OF THE THREE STANDARD SIZES, CUSTOM CLAMSHELLS CAN BE DESIGNED LEVERAGING OFF OF THE

TC - AC - 4HP - DW - S

TRUCOTS

CONDUCTION-COOLED - CC
AIR-COOLED - AC

MODULE HEIGHT

- 0.60" - 3HP
- 0.80" - 4HP
- 1.20" - 6HP
- 1.40" - PM
- 1.46" - MCH

SINGLE WIDE - SW
DOUBLE WIDE - DW

SPLITTER KIT - S
(DOUBLE WIDE ONLY)
BLANK WITHOUT SPLITTER

μ TCA™
PART # BUILDER